

Technical Data for Silicon-free Thermally Conductive Paste W LPK

The thermally conductive paste WLPK is a ceramic-filled silicon-free thermally conductive paste with high thermal conductivity. It consists of synthetic, thermal polymer and enables quick, effective heat dissipation. The paste is especially suitable for silicon sensitive applications. The long term stability of the thermally conductive paste guarantees full functionality during the complete service life of the product. Under normal conditions of use, the paste does not harden, dry out or melt.

Specification:

Consistency: soft / paste-like
 Colour: silver

Thermal Properties

Thermal Resistance R_{th} :	0.006	[K/W]
Thermal Impedance:	2.2 (0.0033)	[°Cmm ² /W] ([KIN ² /W])
Thermal Conductivity:	10.0	[W/mK]

Electrical Properties,

Dielectric Strength E_d ; ac:	conductive	[KV/mm]
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Mechanical Properties

Measured Thickness (+/- 10%):	0.025	[mm]
Viscosity:	60 – 90	[Pas]
Density:	1.4	[g/cm ³]
Working Temperature:	-60 bis +150	[°C]
Weight Loss:	<0.1	[Ma. %]

Long Term Stability of a 0.025 mm Thick Layer (100h / 85°C / 85% relative humidity)

Thermal Resistance R_{th} :	0.006	[K/W]
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Storage Life:

The WLPK thermally conductive paste does not have a special shelf life and so can be stored in a normal climate for up to 12 months. In the event of signs of possible filler material separation the paste must be thoroughly stirred before use.

Advice:

The aforementioned data is consistent with state-of-the-art. Deviations may occur within normal tolerances but do not, however, affect the function. The above specifications have been carefully prepared and checked but are, however, subject to errors and technical changes.

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